

NUMERICAL MODELLING FOR DISTRESSED EMBANKMENTS CONSTRUCTED ON SOFT SOILS CONTAINING GROUND TREATMENT PROVISIONS

SPEAKER:
Ir. YEE THIEN SENG





20 MAY 2025 TUESDAY



5.00PM - 7.00PM



MALAKOFF AUDITORIUM, WISMA IEM

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SYNOPSIS

Numerical modelling of two embankment distresses constructed over soft soils provided with ground treatment techniques using the 2-dimensional finite element analysis will be presented. The constitutive model that handles volumetric changes in soft soils under shear and compression was employed to permit generalised behaviours in the foundation soils to be synthesised.

Difficulties with identifying embankment structural failure from the modelling analyses will be briefly discussed with suggestions to address them.

Some unconventional engineering behaviours in the foundation soils beneath both embankments from the analyses will be shown and their implications highlighted. These behaviours are compared to those established at a trial scheme at the Muar Trial Embankments program.

SPEAKER'S PROFILE

Ir. Yee graduated in civil engineering from the University of Malaya in 1978 and has over the years worked on projects largely involving heavy plant and building foundations as well as large infrastructures. He had also carried out numerous work on distress evaluations and rehabilitation engineering.

In 1994, Ir. Yee set up his own practice, Geo.Consult, to support the construction industry with both expert and specialist advice; in particular on geotechnical engineering aspects. His participation in recent projects of significance are the Kuching Deep Water Port, Shah Alam Expressway, North-South Expressway, Kuantan Port Inner Harbour Development, Kuantan-Kertih Railway and the Rawang-Ipoh Double Tracking Railway.

He has authored/co-authored more than a dozen technical papers in local and international conferences.